

- 2.5-V Virtual Ground for 5-V/GND Analog Systems
- High Output-Current Capability Sink or Source . . . 20 mA Typ
- Micropower Operation . . . 170 μ A Typ

- Excellent Regulation Characteristics
 - Output Regulation
 - 45 μ V Typ at $I_O = 0$ to –10 mA
 - +15 μ V Typ at $I_O = 0$ to +10 mA
 - Input Regulation = 1.5 μ V/V Typ
- Low-Impedance Output . . . 0.0075 Ω Typ
- Macromodel Included

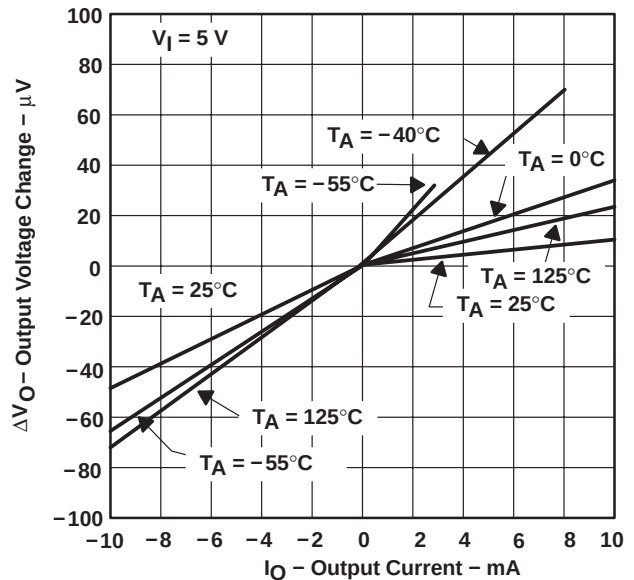
description

In signal-conditioning applications using a single power source, a reference voltage is required for termination of all signal grounds. To accomplish this, engineers have typically used solutions consisting of resistors, capacitors, operational amplifiers, and voltage references. Texas Instruments has eliminated all of those components with one easy-to-use 3-terminal device. That device is the TLE2425 precision virtual ground.

Use of the TLE2425 over other typical circuit solutions gives the designer increased dynamic signal range, improved signal-to-noise ratio, lower distortion, improved signal accuracy, and easier interfacing to ADCs and DACs. These benefits are the result of combining a precision micropower voltage reference and a high-performance precision operational amplifier in a single silicon chip. It is the precision and performance of these two circuit functions together that yield such dramatic system-level performance.

The TLE2425 improves input regulation as well as output regulation and, in addition, reduces output impedance and power dissipation in a majority of virtual-ground-generation circuits. Both input regulation and load regulation exceed 12 bits of accuracy on a single 5-V system. Signal-conditioning front ends of data acquisition systems that push 12 bits and beyond can use the TLE2425 to eliminate a major source of system error.

OUTPUT REGULATION



AVAILABLE OPTIONS

T_A	SMALL OUTLINE (D)	PLASTIC TO-226AA (LP)
0°C to 70°C	TLE2425CD	TLE2425CD
–40°C to 85°C	TLE2425ID	TLE2425ID
–55°C to 125°C	TLE2425MD	—

† The D package is available taped and reeled. Add R suffix to the device type (e.g., TLE2425CDR).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

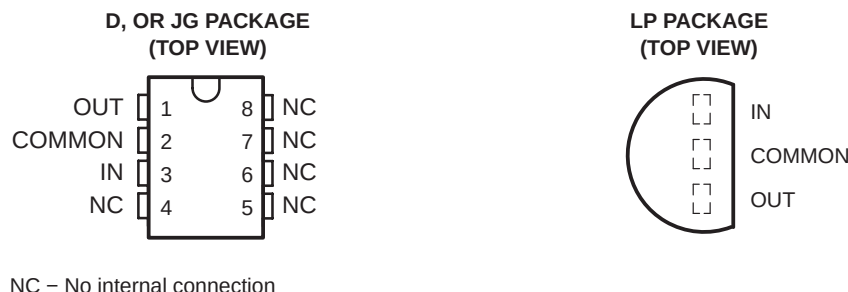
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TLE2425

PRECISION VIRTUAL GROUND

SLOS065D – MARCH 1991 – REVISED APRIL 2002



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Continuous input voltage, V_I	40 V
Output current, I_O	±80 mA
Duration of short-circuit current at (or below) 25°C (see Note 1)	unlimited
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A :	
C-suffix	0°C to 70°C
I-suffix	–40°C to 85°C
M-suffix	–55°C to 125°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: JG or LP package	300°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW
JG	1050 mW	8.4 mW/°C	672 mW	546 mW	210 mW
LP	775 mW	6.2 mW/°C	496 mW	403 mW	155 mW

recommended operating conditions

	C-SUFFIX		I-SUFFIX		M-SUFFIX		UNIT
	MIN	MAX	MIN	MAX	MIN	MAX	
Input voltage, V_I	4	40	4	40	4	40	V
Operating free-air temperature, T_A	0	70	–40	85	–55	125	°C

electrical characteristics at specified free-air temperature, $V_I = 5\text{ V}$, $I_O = 0$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A [†]	TLE2425C			UNIT
				MIN	TYP	MAX	
Output voltage			25°C	2.48	2.5	2.52	V
			Full range	2.47		2.53	
Temperature coefficient of output voltage			25°C	20			ppm/°C
Bias current	I _O = 0		25°C	170			μA
			Full range	250			
Input voltage regulation	V _I = 4.5 V to 5.5 V		25°C	1.5			μV
			Full range	25			
	V _I = 4 V to 40 V		25°C	1.5			μV/V
			Full range	25			
Ripple rejection	f = 120 Hz, ΔV _{I(PP)} = 1 V		25°C	80			dB
Output voltage regulation (source current) [‡]	I _O = 0 to −10 mA		25°C	−160	−45	160	μV
			Full range	−250		250	
	I _O = 0 to −20 mA		25°C	−450	−150	450	
Output voltage regulation (sink current) [‡]	I _O = 0 to 10 mA		25°C	−160	15	160	μV
			Full range	−250		250	
	I _O = 0 to 20 mA		25°C	−235	65	235	
Long-term drift of output voltage	Δt = 1000 h, Noncumulative		25°C	15			ppm
Output impedance			25°C	7.5			mΩ
Short-circuit output current (sink current)	V _O = 5 V		25°C	30	55		mA
Short-circuit output current (source current)	V _O = 0			−30	−50		
Output noise voltage, rms	f = 10 Hz to 10 kHz		25°C	100			μV
Output voltage response to output current step	V _O to 0.1%, I _O = ±10 mA	C _L = 0	25°C	110			μs
		C _L = 100 pF		115			
	V _O to 0.01%, I _O = ±10 mA	C _L = 0		180			
		C _L = 100 pF		180			
Output voltage response to input voltage step	V _I = 4.5 to 5.5 V, V _O to 0.1%		25°C	12			μs
	V _I = 4.5 to 5.5 V, V _O to 0.01%			30			
Output voltage turn-on response	V _I = 0 to 5 V, V _O to 0.1%		25°C	125			μs
	V _I = 0 to 5 V, V _O to 0.01%			210			

† Full range is 0°C to 70°C.

‡ The listed values are not production tested.

TLE2425

PRECISION VIRTUAL GROUND

SLOS065D – MARCH 1991 – REVISED APRIL 2002

electrical characteristics at specified free-air temperature, $V_I = 5\text{ V}$, $I_O = 0$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A [†]	TLE2425I			UNIT	
				MIN	TYP	MAX		
Output voltage			25°C	2.48	2.5	2.52	V	
			Full range	2.47		2.53		
Temperature coefficient of output voltage			25°C	20			ppm/°C	
Bias current	I _O = 0		25°C	170			μA	
			Full range	250				
Input voltage regulation	V _I = 4.5 V to 5.5 V		25°C	1.5			μV	
			Full range	75				
	V _I = 4 V to 40 V		25°C	1.5			μV/V	
			Full range	75				
Ripple rejection	f = 120 Hz, ΔV _{I(PP)} = 1 V		25°C	80			dB	
Output voltage regulation (source current) [‡]	I _O = 0 to −10 mA		25°C	−160	−45	160	μV	
			Full range	−250		250		
	I _O = 0 to −20 mA		25°C	−450	−150	450		
Output voltage regulation (sink current) [‡]	I _O = 0 to 8 mA		25°C	−160	15	160	μV	
			Full range	−250		250		
	I _O = 0 to 20 mA		25°C	−235	65	235		
Long-term drift of output voltage	Δt = 1000 h, Noncumulative		25°C	15			ppm	
Output impedance			25°C	7.5			22.5	mΩ
Short-circuit output current (sink current)	V _O = 5 V		25°C	30	55		mA	
Short-circuit output current (source current)	V _O = 0			−30	−50			
Output noise voltage, rms	f = 10 Hz to 10 kHz		25°C	100			μV	
Output voltage response to output current step	V _O to 0.1%, I _O = ±10 mA	C _L = 0	25°C	110			μs	
		C _L = 100 pF		115				
	V _O to 0.01%, I _O = ±10 mA	C _L = 0		180				
		C _L = 100 pF		180				
Output voltage response to input voltage step	V _I = 4.5 to 5.5 V, V _O to 0.1%		25°C	12			μs	
	V _I = 4.5 to 5.5 V, V _O to 0.01%			30				
Output voltage turn-on response	V _I = 0 to 5 V, V _O to 0.1%		25°C	125			μs	
	V _I = 0 to 5 V, V _O to 0.01%			210				

† Full range is -40°C to 85°C.

‡ The listed values are not production tested.



electrical characteristics at specified free-air temperature, $V_I = 5\text{ V}$, $I_O = 0$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A [†]	TLE2425M			UNIT	
				MIN	TYP	MAX		
Output voltage			25°C	2.48	2.5	2.52	V	
			Full range	2.47		2.53		
Temperature coefficient of output voltage			25°C	20			ppm/°C	
Bias current	I _O = 0	25°C	170			250	μA	
		Full range	250					
Input voltage regulation	V _I = 4.5 V to 5.5 V	25°C	1.5			20	μV	
		Full range	100					
	V _I = 4.5 V to 40 V	25°C	1.5			20	μV/V	
		Full range	100					
Ripple rejection	f = 120 Hz,	ΔV _I (PP) = 1 V	25°C	80			dB	
Output voltage regulation (source current) [‡]	I _O = 0 to −10 mA	25°C	−160	−45	160	μV		
		Full range	−250		250			
	I _O = 0 to −20 mA	25°C	−450	−150	450			
Output voltage regulation (sink current) [‡]	I _O = 0 to 3 mA	25°C	−160	15	160	μV		
		Full range	−250		250			
	I _O = 0 to 20 mA	25°C	−235	65	235			
Long-term drift of output voltage	Δt = 1000 h,	Noncumulative	25°C	15			ppm	
Output impedance			25°C	7.5			22.5	mΩ
Short-circuit output current (sink current)	V _O = 5 V		25°C	30	55		mA	
Short-circuit output current (source current)	V _O = 0			−30	−50			
Output noise voltage, rms	f = 10 Hz to 10 kHz		25°C	100			μV	
Output voltage response to output current step	V _O to 0.1%, I _O = ±10 mA	C _L = 0	25°C	110			μs	
		C _L = 100 pF		115				
	V _O to 0.01%, I _O = ±10 mA	C _L = 0		180				
		C _L = 100 pF		180				
Output voltage response to input voltage step	V _I = 4.5 to 5.5 V, V _O to 0.1%	25°C	12			μs		
	V _I = 4.5 to 5.5 V, V _O to 0.01%		30					
Output voltage turn-on response	V _I = 0 to 5 V, V _O to 0.1%	25°C	125			μs		
	V _I = 0 to 5 V, V _O to 0.01%		210					

[†] Full range is -55°C to 125°C.

[‡] The listed values are not production tested.

TLE2425

PRECISION VIRTUAL GROUND

SLOS065D – MARCH 1991 – REVISED APRIL 2002

TYPICAL CHARACTERISTICS

Table Of Graphs

		FIGURE
Output voltage	Distribution	1
	vs Free-air temperature	2
Output voltage hysteresis	vs Free-air temperature	3
Input bias current	vs Input voltage	4
	vs Free-air temperature	5
Input voltage regulation		6
Ripple rejection	vs Frequency	7
Output voltage regulation		8
Output impedance	vs Frequency	9
Short-circuit output current	vs Free-air temperature	10
Spectral noise voltage density	vs Frequency	11
Wide-band noise voltage	vs Frequency	12
Output voltage change with current step	vs Time	13
Output voltage change with voltage step	vs Time	14
Output voltage power-up response	vs Time	15
Output current	vs Load capacitance	16



TYPICAL CHARACTERISTICS†

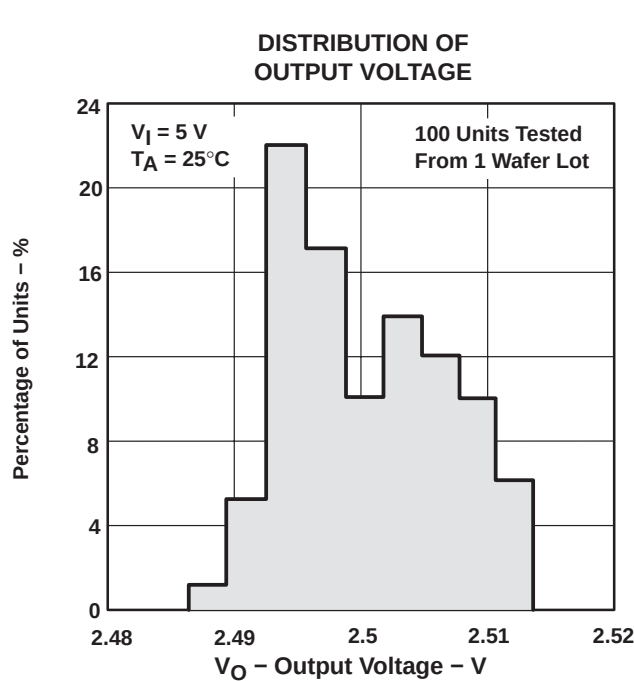


Figure 1

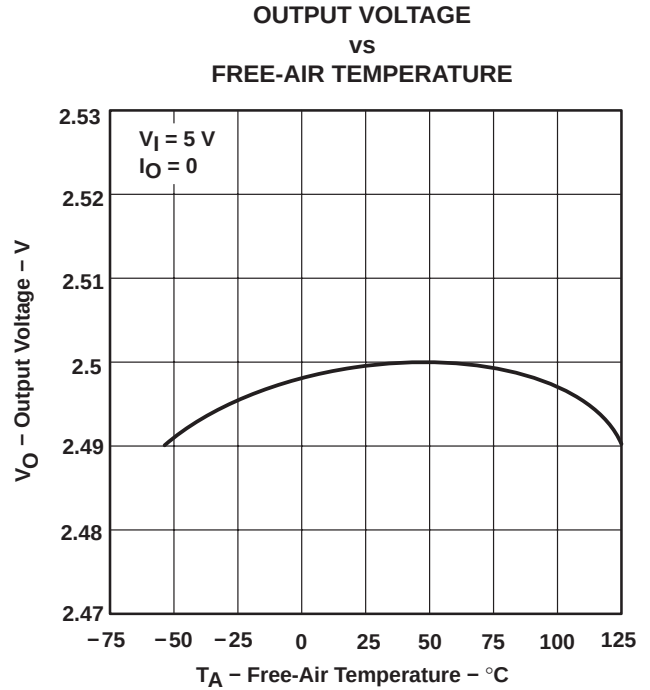


Figure 2

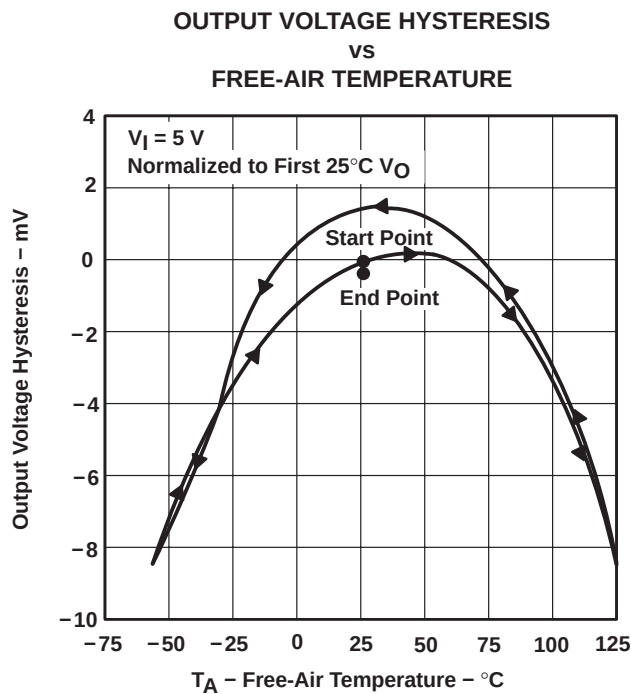


Figure 3

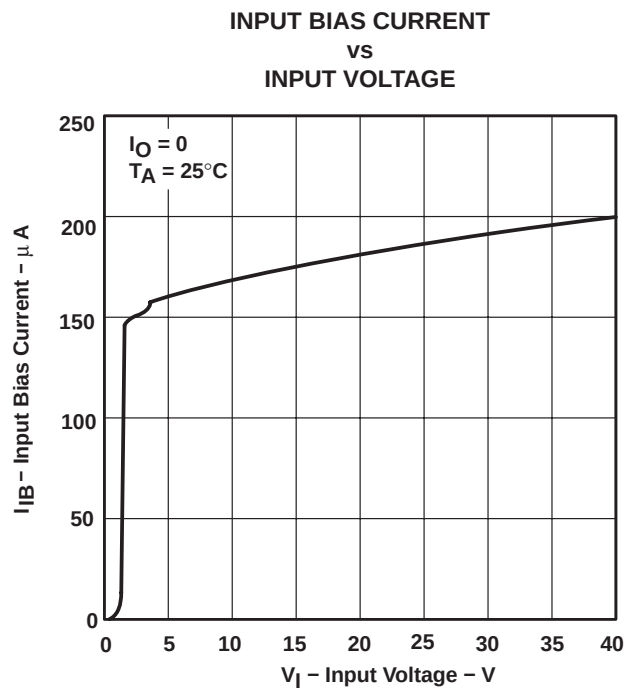


Figure 4

† Data at high and low temperatures are applicable within rated operating free-air temperature ranges of the various devices.

TLE2425 PRECISION VIRTUAL GROUND

SLOS065D – MARCH 1991 – REVISED APRIL 2002

TYPICAL CHARACTERISTICS†

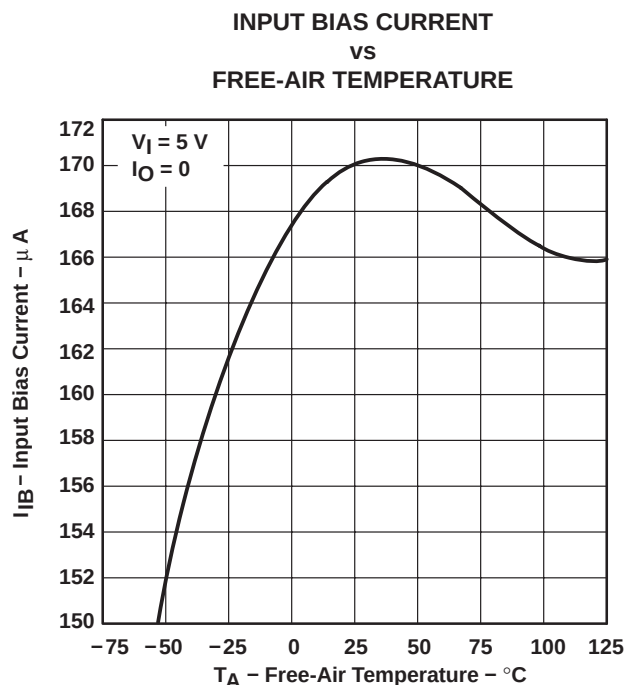


Figure 5

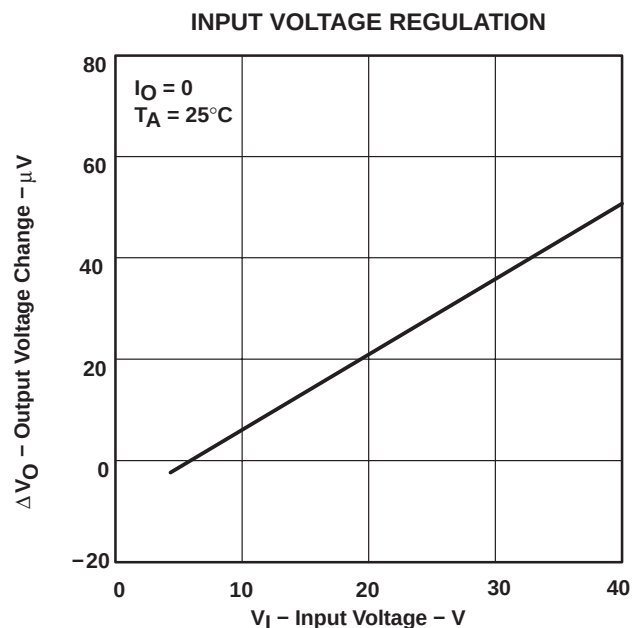


Figure 6

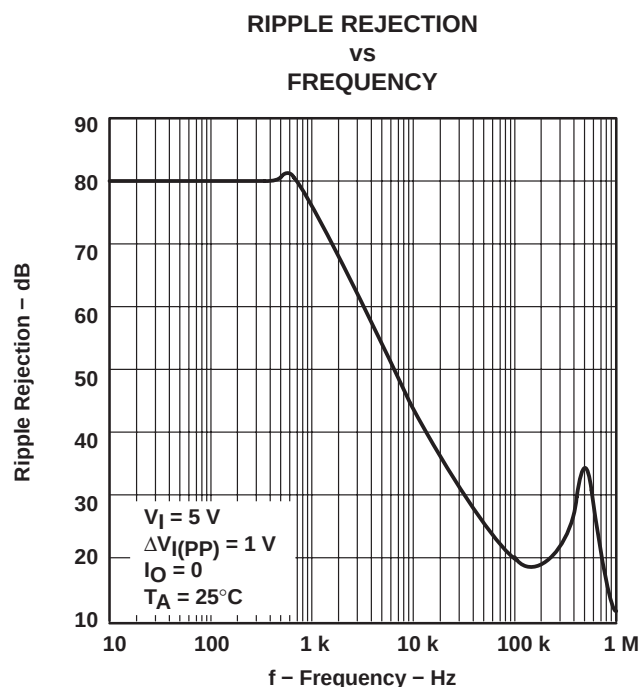


Figure 7

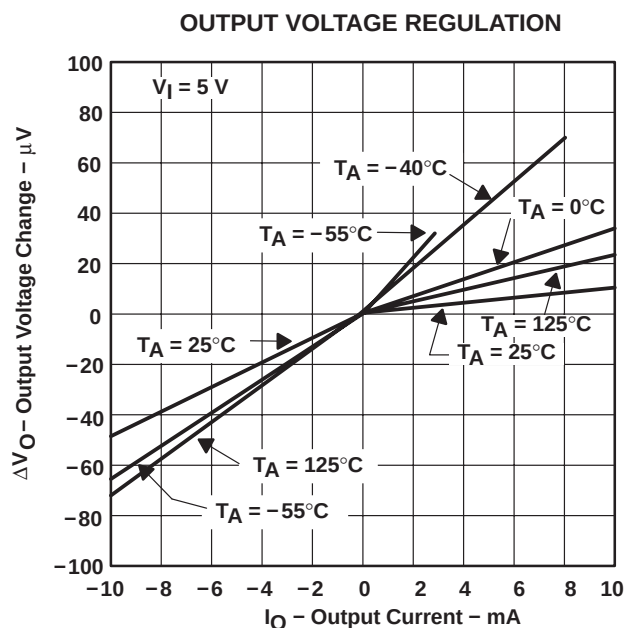


Figure 8

† Data at high and low temperatures are applicable within rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

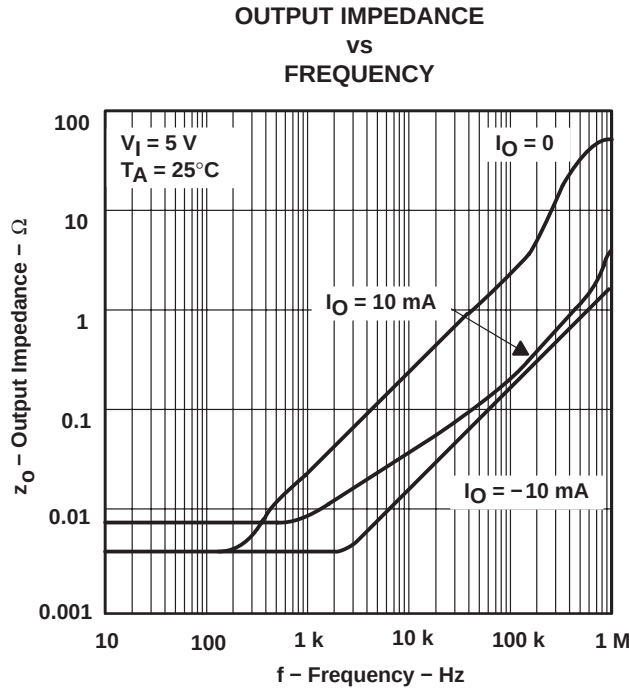


Figure 9

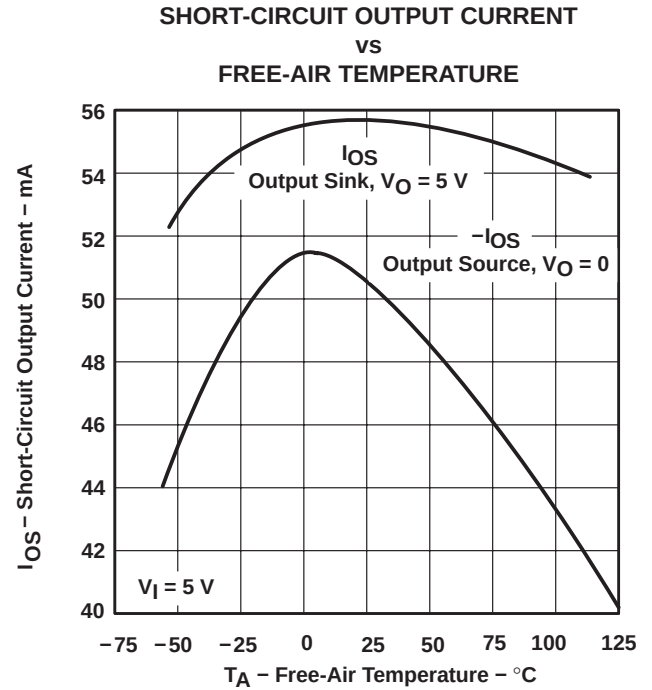


Figure 10

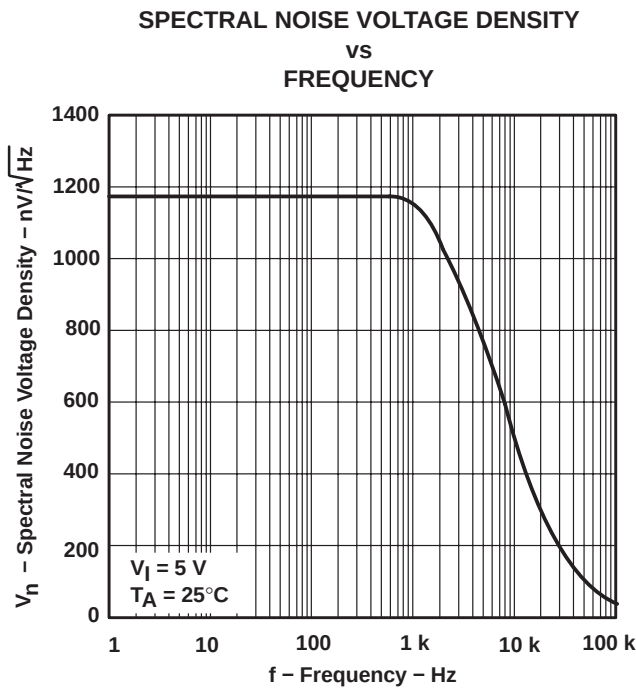


Figure 11

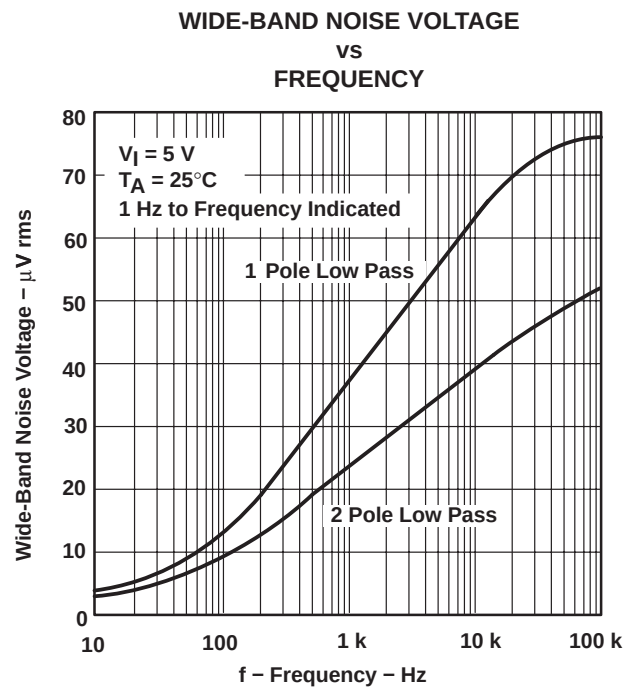


Figure 12

TYPICAL CHARACTERISTICS

**OUTPUT VOLTAGE RESPONSE
 TO OUTPUT CURRENT STEP**

**VS
 TIME**

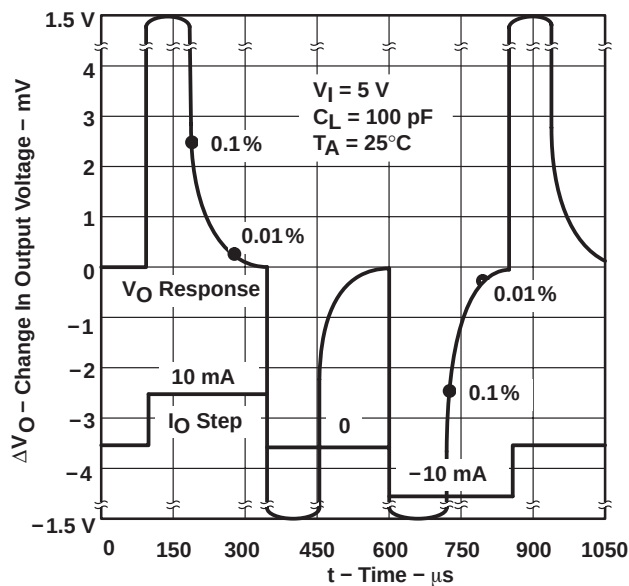


Figure 13

**OUTPUT VOLTAGE RESPONSE
 TO INPUT VOLTAGE STEP**

**VS
 TIME**

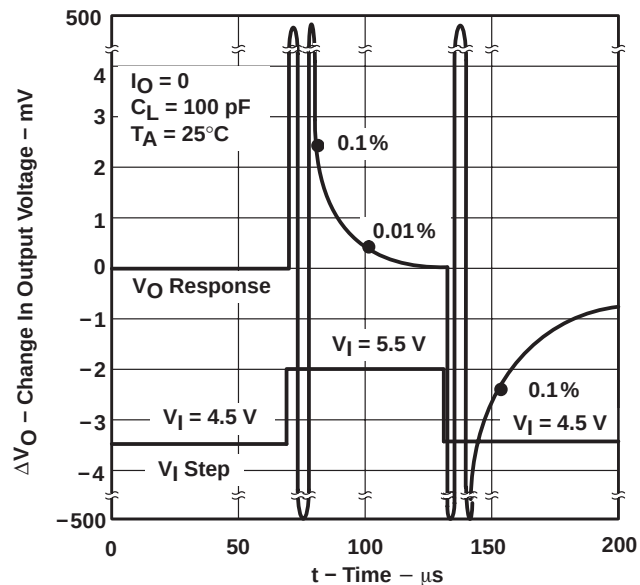


Figure 14

OUTPUT VOLTAGE POWER-UP RESPONSE

**VS
 TIME**

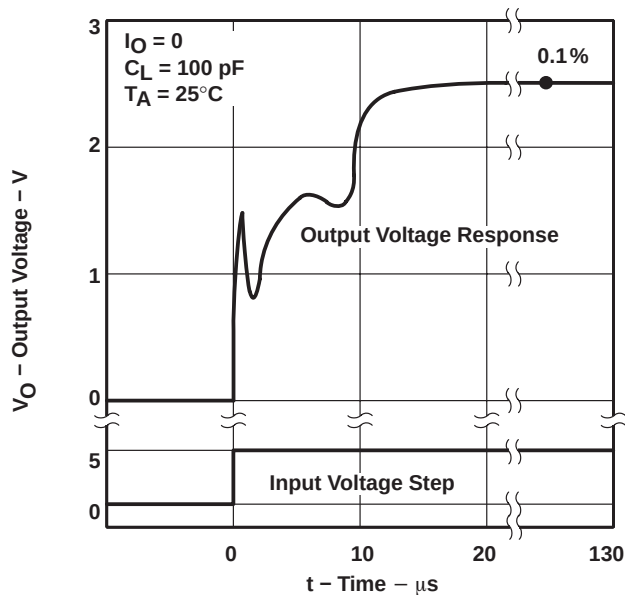


Figure 15

**STABILITY RANGE
 OUTPUT CURRENT**

**VS
 LOAD CAPACITANCE**

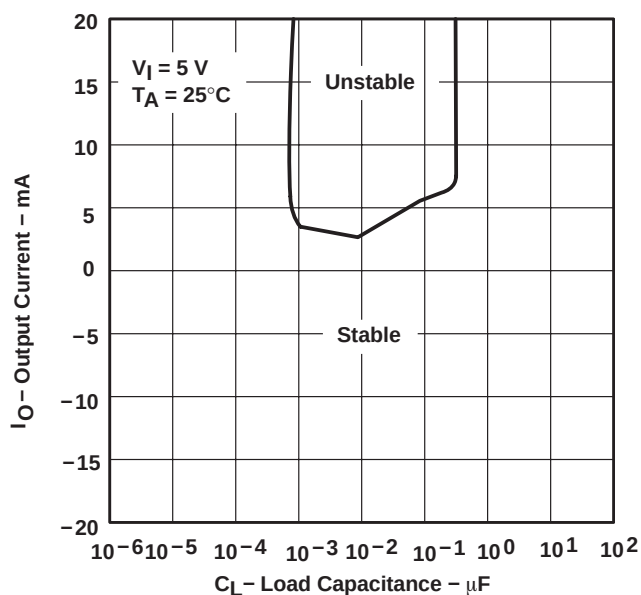


Figure 16

macromodel information

```

*   TLE2425 OPERATIONAL AMPLIFIER "MACROMODEL" SUBCIRCUIT
*   CREATED USING PARTS RELEASE 4.03 ON 08/21/90 AT 13:51
*   REV (N/A)      SUPPLY VOLTAGE: 5 V
*   CONNECTIONS:  INPUT
*                   |      COMMON
*                   |      OUTPUT
*                   |      |
*                   |      |
*                   |      |
.SUBCKT TLE2425 3 4 5
*
*
*   OPAMP SECTION
C1      11 12 21.66E-12
C2      6 7 30.00E-12
C3      87 0 10.64E-9
CPSR    85 86 15.9E-9
DCM+    81 82 DX
DCM-    83 81 DX
DC      5 53 DX
DE      54 5 DX
DLN     92 90 DX
DLP     90 91 DX
DP      4 3 DX
ECMR    84 99 (2,99) 1
EGND    99 0 POLY(2) (3,0) (4,0) 0 .5 .5
EPSR    85 0 POLY(1) (3,4) -16.22E-6 3.24E-6
ENSE    89 2 POLY(1) (88,0) 120E-6 1
FB      7 99 POLY(6) VB VC VE VLP VLN VPSR 0 74.8E6 -10E6 10E6 10E6
+ -10E6 74E6
GA      6 0 11 12 320.4E-6
GCM     0 6 10 99 1.013E-9
GPSR    85 86 (85,86) 100E-6
GRC1    4 11 (4,11) 3.204E-4
GRC2    4 12 (4,12) 3.204E-4
GRE1    13 10 (13,10) 1.038E-3
GRE2    14 10 (14,10) 1.038E-3
HLIM    90 0 VLIM 1K
HCMR    80 1 POLY(2) VCM+ VCM- 0 1E2 1E2
IRP     3 4 146E-6
IEE     3 10 DC 24.05E-6
IIO     2 0 .2E-9
I1      88 0 1E-21
Q1      11 89 13 QX
Q2      12 80 14 QX
R2      6 9 100.0E3
RCM     84 81 1K
REE     10 99 8.316E6
RN1     87 0 2.55E8
RN2     87 88 11.67E3

```

TLE2425

PRECISION VIRTUAL GROUND

SLOS065D – MARCH 1991 – REVISED APRIL 2002

macromodel information (continued)

```
RO1      8  5  63
RO2      7 99  62
VCM+    82 99  1.0
VCM-    83 99 -2.3
VB       9  0  DC  0
VC       3 53  DC  1.400
VE      54  4  DC  1.400
VLIM     7  8  DC  0
VLP     91  0  DC  30
VLN      0 92  DC  30
VPSR     0 86  DC  0
RFB      5  2  1K
RIN     30  1  1K
RCOM    34  4  .1
*REGULATOR SECTION
RG1     30  0  20MEG
RG2     30 31  .2
RG3     31 35  400K
RG4     35 34  411K
RG5     31 36  25MEG
HREG    31 32  POLY(2)   VPSET VNSET  0  1E2 1E2
VREG    32 33  DC  0V
EREG    33 34  POLY(1)   (36,34)  1.23 1
VADJ    36 34  1.27V
HPSET   37  0  VREG  1.030E3
VPSET   38  0  DC  20V
HNSET   39  0  VREG  6.11E5
VNSET   40  0  DC -20V
DSUB     4 34  DX
DPOS    37 38  DX
DNNEG   40 39  DX
.MODEL DX  D(IS=800.0E-18)
.MODEL QX  PNP(IS=800.0E-18 BF=480)
.ENDS
```



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9555601Q2A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
5962-9555601QPA	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-55 to 125		
TLE2425CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2425C	Samples
TLE2425CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2425C	Samples
TLE2425CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2425C	Samples
TLE2425CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2425C	Samples
TLE2425CLP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type		2425C	Samples
TLE2425CLPR	OBSOLETE	TO-92	LP	3		TBD	Call TI	Call TI			
TLE2425CPS	ACTIVE	SO	PS	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Q2425	Samples
TLE2425CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Q2425	Samples
TLE2425ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2425I	Samples
TLE2425IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2425I	Samples
TLE2425IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2425I	Samples
TLE2425IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2425I	Samples
TLE2425ILP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type		2425I	Samples
TLE2425ILPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type		2425I	Samples
TLE2425MD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2425M	Samples
TLE2425MDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2425M	Samples
TLE2425MDR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-55 to 125	2425M	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLE2425MDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2425M	Samples
TLE2425MFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
TLE2425MJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-55 to 125		
TLE2425MJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI	-55 to 125		
TLE2425MLP	OBSOLETE	TO-92	LP	3		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

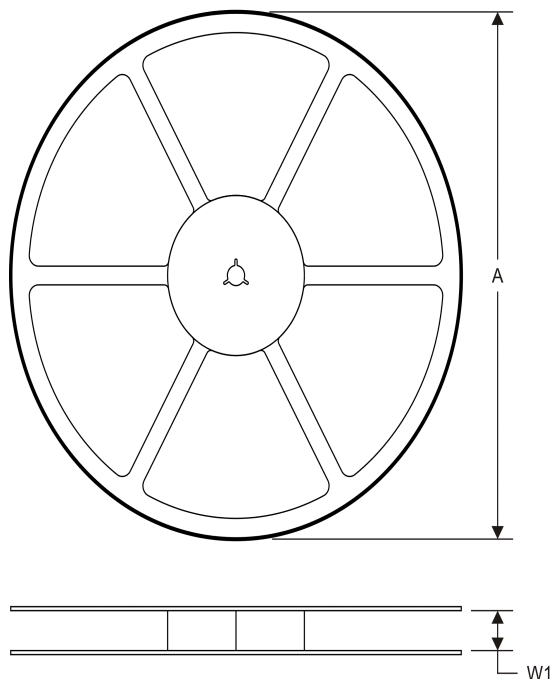
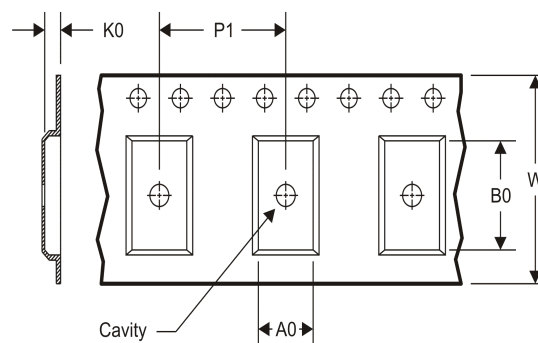
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


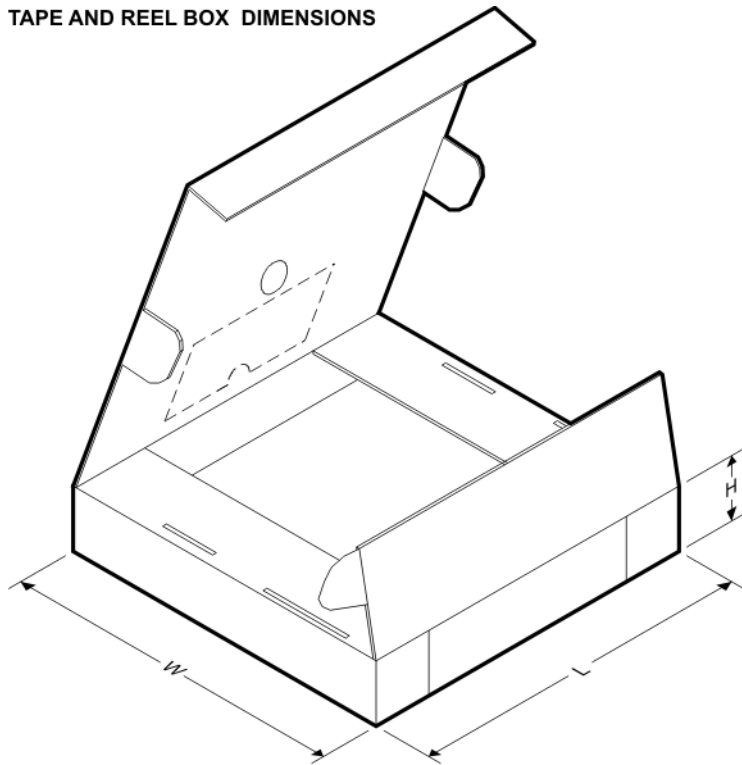
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLE2425CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLE2425CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
TLE2425IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

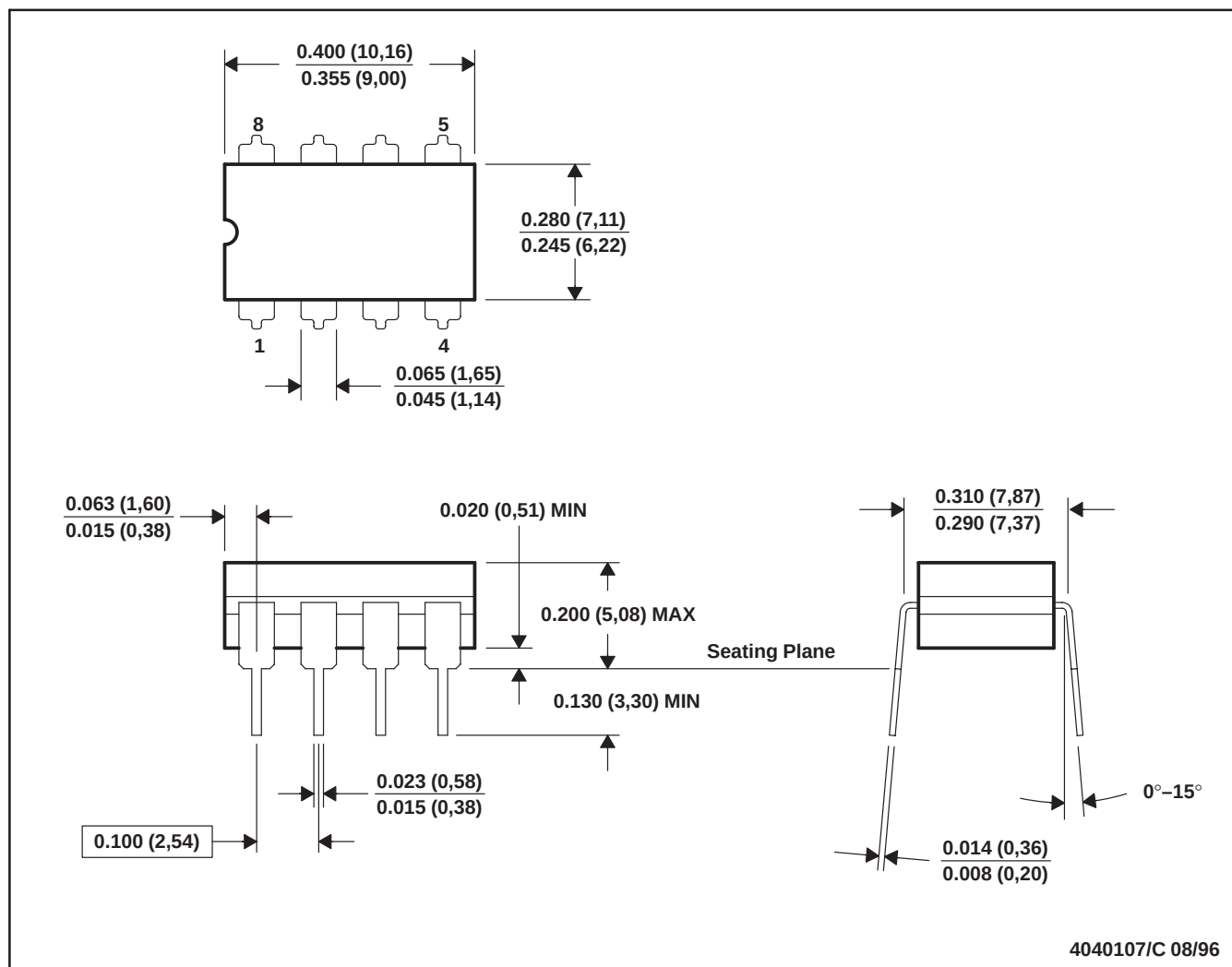


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLE2425CDR	SOIC	D	8	2500	367.0	367.0	35.0
TLE2425CPSR	SO	PS	8	2000	367.0	367.0	38.0
TLE2425IDR	SOIC	D	8	2500	367.0	367.0	35.0

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE

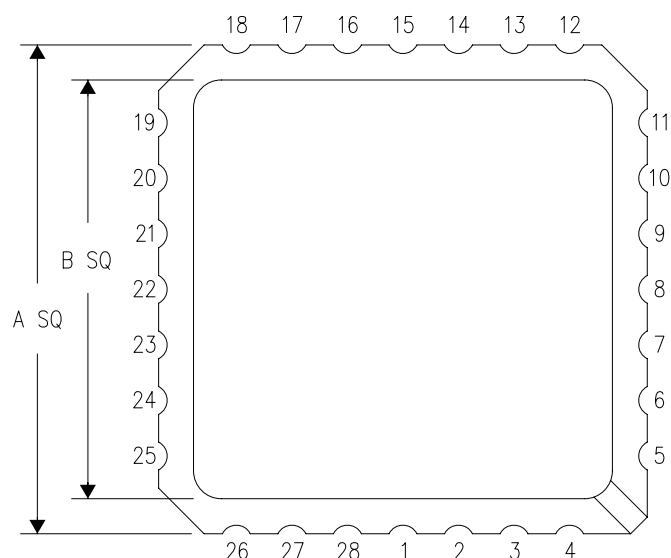


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP1-T8

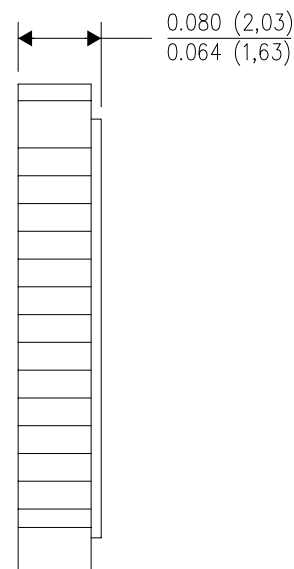
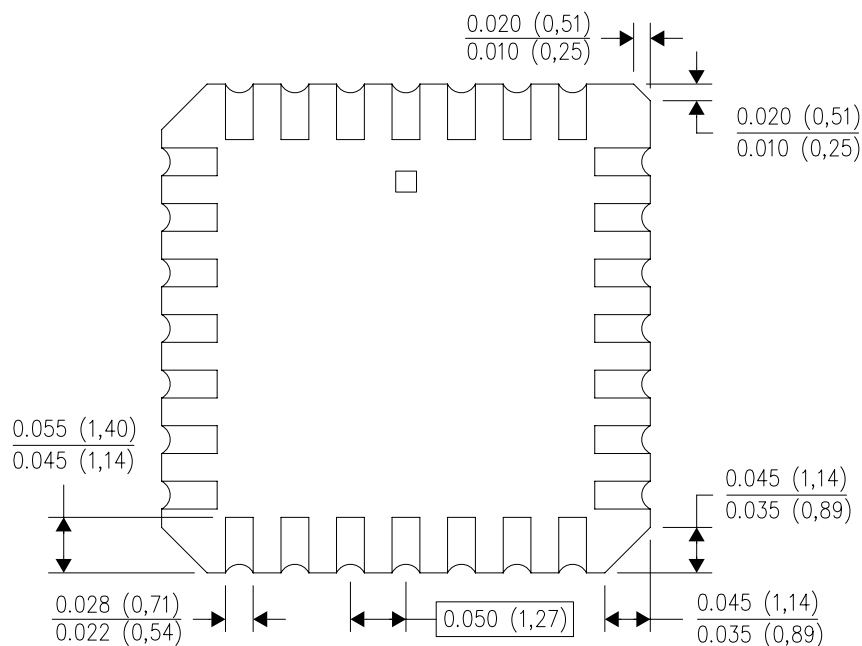
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

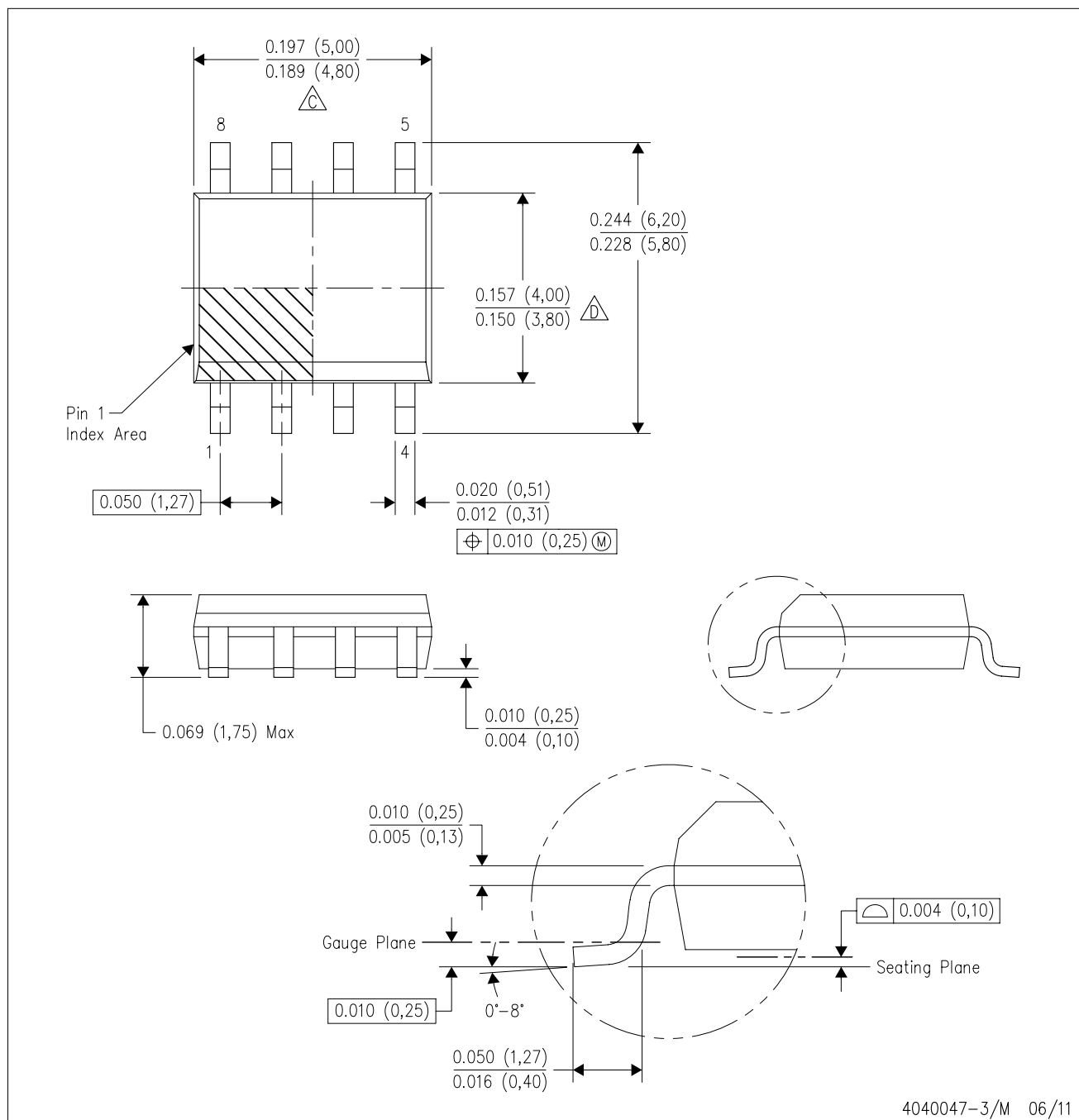


4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

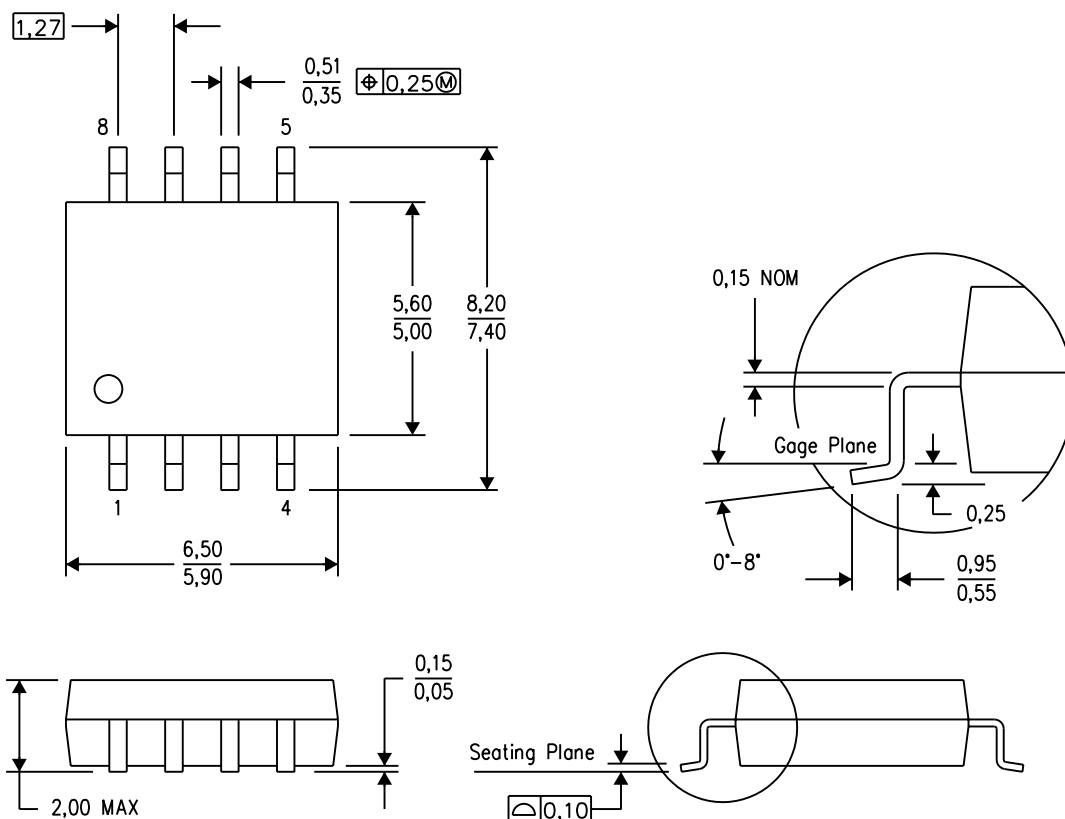


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

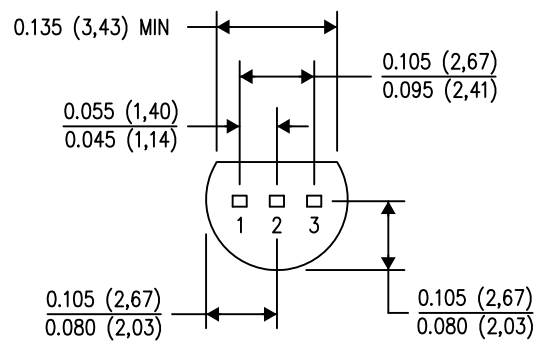
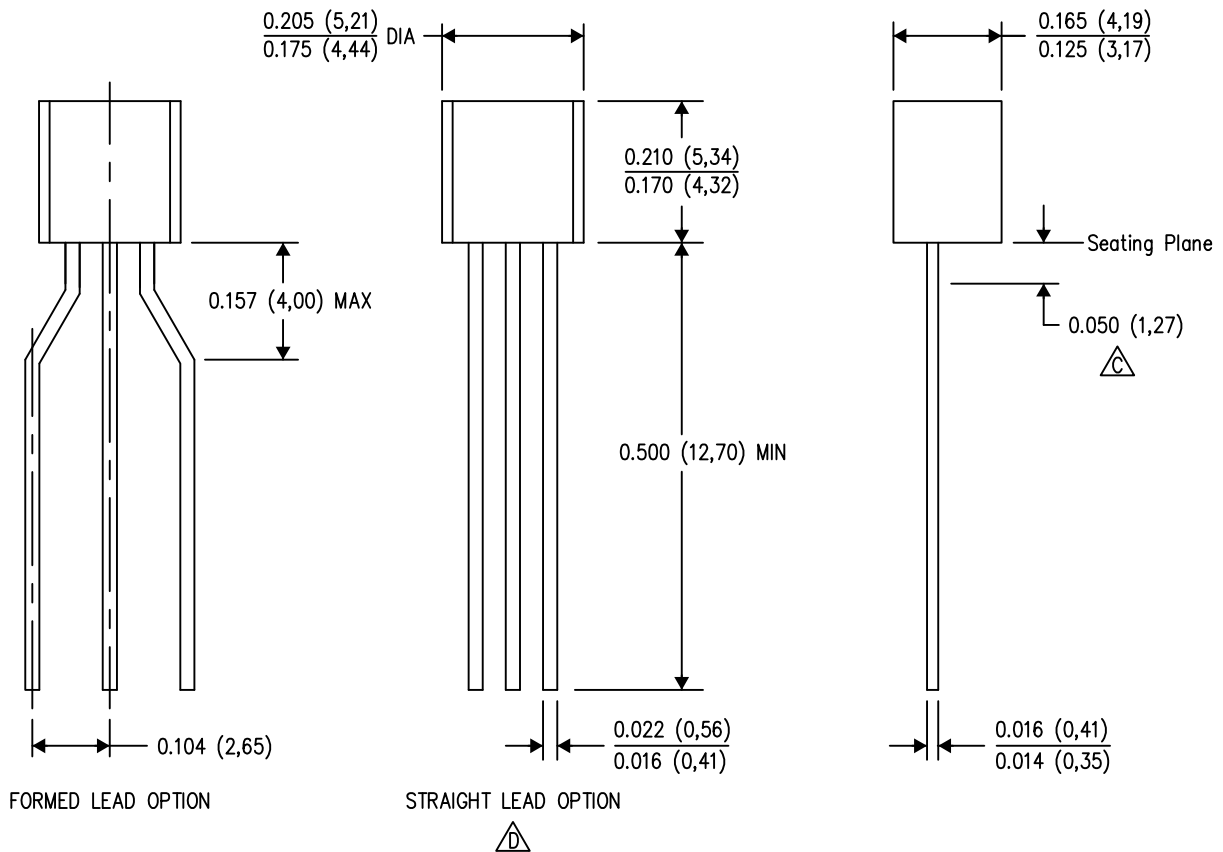


4040063/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE

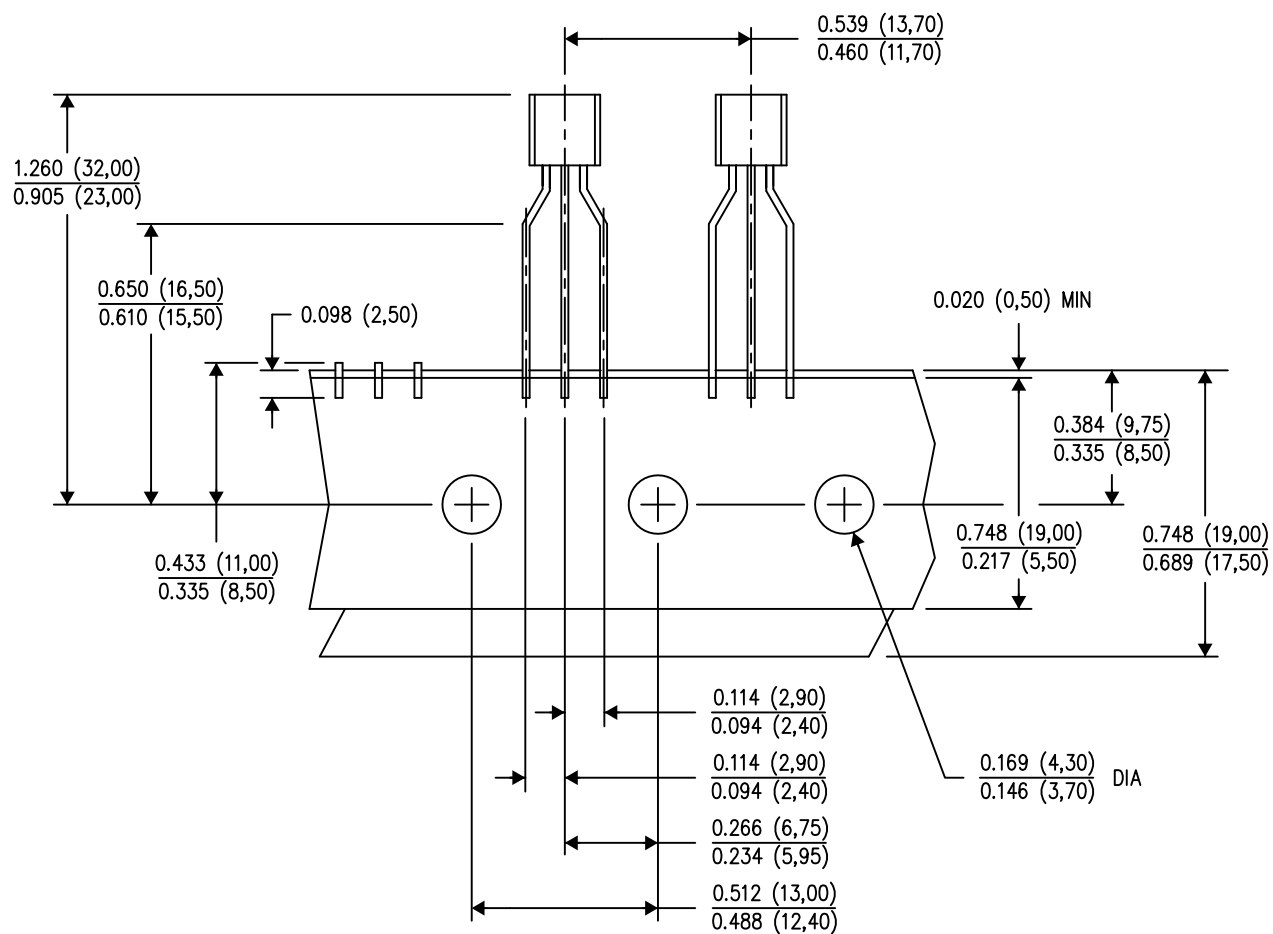


4040001-2/E 08/13

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Lead dimensions are not controlled within this area.
 - D. Falls within JEDEC TO-226 Variation AA (TO-226 replaces TO-92).
 - E. Shipping Method:
 Straight lead option available in bulk pack only.
 Formed lead option available in tape & reel or ammo pack.
 Specific products can be offered in limited combinations of shipping mediums and lead options.
 Consult product folder for more information on available options.

LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



TAPE & REEL

4040001-3/E 08/13

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Tape and Reel information for the Formed Lead Option package.

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